Advance Product Change Notification

202502007A : PCA9450 / MP90 Dual Wafer Fabrication Source Expansion from SSMC to PSMC

Note: This notice is NXP Company Proprietary.

Issue Date: Feb 22, 2025

Here is your personalized communication about an NXP notification.
For detailed information we invite you to view this notification online

Management summary

NXP Semiconductors announces the addition of wafer fab Powerchip Semiconductor Manufacturing Corporation (PSMC, Hsinchu Taiwan) for PCA9450 / MP90 products. Currently product is sourced from wafer fab Systems on Silicon Manufacturing Company (SSMC, Singapore). The addition of Powerchip wafer fab creates more sourcing reliability, flexibility, and capacity expansion.

Change Category

[ ]Wafer Fab Process	[ ]Assembly Process	[ ]Product Marking	[ ]Test Process	[ ]Design
[ ]Wafer Fab Materials	[ ]Assembly Materials	[ ]Mechanical Specification	[ ]Test Equipment	[ ]Errata
[X]Wafer Fab Location	[ ]Assembly Location	[ ]Packing/Shipping/Labeling	[ ]Test Location	[ ]Electrical spec./Test coverage
[ ]Firmware	[ ]Other			

Notification Overview

Description

NXP Semiconductors announces the addition of wafer fab Powerchip Semiconductor Manufacturing Corporation (PSMC, Hsinchu Taiwan) for PCA9450 / MP90 products. Currently product is sourced from wafer fab Systems on Silicon Manufacturing Company (SSMC, Singapore). The addition of Powerchip wafer fab creates more sourcing reliability, flexibility, and capacity expansion.

The dual wafer fab sourcing of the PCA9450x / MP90 products from SSMC and Powerchip results in:
- No change to orderable part number / 12NC
- No change to data sheet
- No change to Bill of Material (BOM) items
- No change to Assembly and Package site locations

Upon qualification completion, NXP will issue a Final PCN to relay qualification results.

Please see the attached files for additional details.

Reason

The addition of Powerchip wafer fab creates more sourcing reliability, flexibility, and capacity expansion.

Identification of Affected Products

Top Side Marking

Topside marking will reflect the Powerchip wafer fab marking; the wafer fab in marking line D will change to "S" for Powerchip.

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment Jun 01, 2025

Anticipated Impact on Form, Fit, Function, Reliability or Quality

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No Impact on form, fit, function, reliability or quality

Disposition of Old Products

Dual fab sourcing - no impact.

Additional information

Self qualification:view online

Timing and Logistics

The Self Qualification Report will be ready on Apr 01, 2025.

The Final PCN is planned to be issued on: Apr 30, 2025.

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Mar 24, 2025.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards. Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

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